AUTOMOTIVE

ROHS

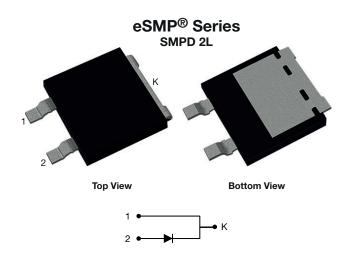
HALOGEN

FREE



Vishay General Semiconductor

Surface-Mount ESD Capability Rectifiers

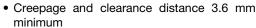


LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS					
I _{F(AV)}	12 A				
V _{RRM}	400 V, 600 V				
I _{FSM}	125 A				
V_F at $I_F = 12 \text{ A } (T_J = 125 ^{\circ}\text{C})$	0.96 V				
I _R	20 μΑ				
T _J max.	175 °C				
Package	SMPD 2L				
Circuit configuration	Single				

FEATURES





- Ideal for automated placement
- Oxide planar chip junction
- Low forward voltage drop
- ESD capability
- AEC-Q101 qualified available
- Meets MSL level 1, per J-STD-020, LF maximum peak 260 °C
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

TYPICAL APPLICATIONS

General purpose, power line polarity protection, in both consumer and automotive on board charger (OBC) applications.

MECHANICAL DATA

Case: SMPD 2L

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 2 whisker test, HM3 suffix meets JESD 201 class 2 whisker test

Polarity: as marked

MAXIMUM RATINGS (T _J = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	SE12DTG	SE12DTJ	UNIT		
Device code		SE12DTG	SE12DTJ			
Maximum repetitive peak reverse voltage	V_{RRM}	400	600	V		
Maximum DC forward current	I _F ⁽¹⁾	12		۸		
Maximum DC forward current	I _F ⁽²⁾	3.2		Α Α		
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I _{FSM}	125		А		
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +175		°C		

Notes

⁽¹⁾ With heatsink

⁽²⁾ Free air, mounted on recommended copper pad area



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ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I _F = 6 A	– T _J = 25 °C		0.95	-	V
	I _F = 12 A		V _F (1)	1.04	1.15	
	I _F = 6 A	- T _J = 125 °C	V _F (·)	0.85	-	
	I _F = 12 A			0.96	1.10	
Reverse current	Date d V	T _J = 25 °C	-	20		
	Rated V _R	T _J = 125 °C	I _R ⁽²⁾	27	150	μΑ
Typical reverse recovery time	I _F = 0.5 A, I _R = 1.0 A, I _{rr} = 0.25 A		t _{rr}	3000	-	ns
Typical junction capacitance	4.0 V, 1 MHz		CJ	90	-	pF

Notes

(1) Pulse test: 300 μs pulse width, 1 % duty cycle

⁽²⁾ Pulse test: Pulse width \leq 40 ms

THERMAL CHARACTERISTICS (T _A = 25 °c unless otherwise noted)					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Thormal registance	R _{θJA} (1)(2)	60	75	°C/W	
Thermal resistance	R ₀ JC (3)	1.6	2	C/VV	

Notes

- $^{(1)}$ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
- (2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint
- (3) Thermal resistance junction-to-mount to follow JEDEC® 51-14 transient dual interface test method (TDIM)

IMMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS ($T_A = 25~^{\circ}\text{C}$ unless otherwise noted)						
STANDARD	TEST TYPE TEST CONDITIONS SYMBOL CLASS VALUE					
AEC-Q101-001	Human body model (contact mode) $C = 100 \text{ pF}, R = 1.5 \text{ k}\Omega$ V_C H3B $> 8 \text{ kV}$					

ORDERING INFORMATION (Example)						
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE		
SE12DTJ-M3/I	0.52	I	2000 / reel	13" diameter plastic tape and reel		
SE12DTJHM3/I (1)	0.52	I	2000 / reel	13" diameter plastic tape and reel		

Note

(1) AEC-Q101 qualified



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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

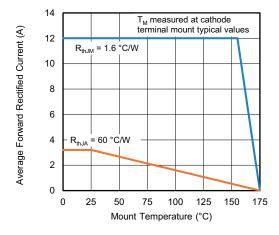


Fig. 1 - Forward Current Derating Curve

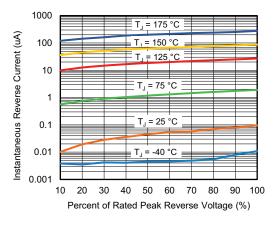


Fig. 4 - Typical Reverse Leakage Characteristics

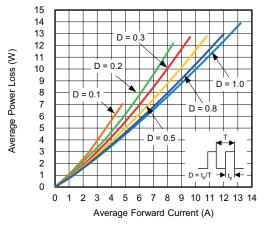


Fig. 2 - Forward Power Loss Characteristics

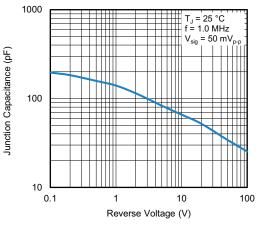


Fig. 5 - Typical Junction Capacitance

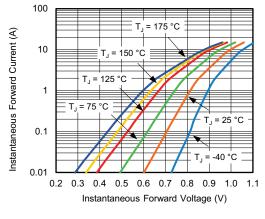


Fig. 3 - Typical Instantaneous Forward Characteristics

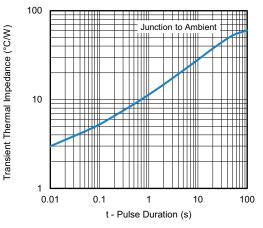


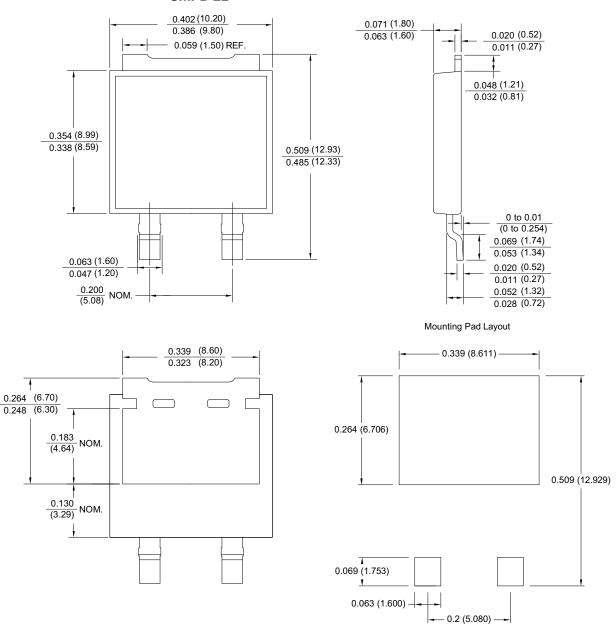
Fig. 6 - Typical Transient Thermal Impedance



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PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





Note

• The suggested mounting pad layout is provided for reference only, as actual pad layouts may vary depending on application



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